

BIRLA INSTITUTE OF TECHNOLOGY AND SCIENCE, PILANI
COMPREHENSIVE EXAMINATION
 Semester I: 2023-2024
Part A: Closed Book
MEL G631: Physics and Modelling of Microelectronic Devices

Date: **08/12/2022**

Maximum Marks: **40**

Maximum Time: **90 minutes**

Given (Use, if not specified in the questions):

$q=1.6 \times 10^{-19}$ C, $k=1.38 \times 10^{-23}$ m²kg s⁻²k⁻¹, $T=300$ K, $kT/q=0.026$ V, $\epsilon_0=8.85 \times 10^{-14}$ F/cm

Si: $\epsilon_r=11.8$, $n_i=1.45 \times 10^{10}$ cm⁻³, $E_g=1.12$ eV, $\mu_n=1300$ cm²/V-s, $\mu_p(\text{Si})=480$ cm²/V-s, $q\chi=4.05$ eV,

$N_C=2.8 \times 10^{19}$ cm⁻³, $N_V=1.04 \times 10^{19}$ cm⁻³.

Au: $\phi_M=4.75$ eV

Answer should be very brief and to the point.

- Q1. What is the probability of finding of an electron at the conduction band [$f(E_C)$.] of pure Silicon at 20°C ? [2]

Ans:

- Q2. Consider a P⁺n junction, where N_D is tripled. If everything else remains same, how do the parameters listed below change. Tick the correct answer. [2]

(a) Depletion capacitance: Increase / Decrease

(b) Built-in potential: Increase / Decrease

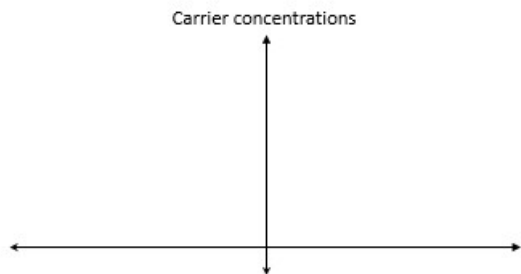
(c) Breakdown voltage: Increase / Decrease

(d) Ohmic losses: Increase / Decrease

- Q3. For a Si p-n junction, $N_A=N_D=10^{17}$ cm⁻³. Find the applied reverse bias voltage when maximum electric field will be 5×10^5 V/cm. (T = 300 k) [2]

Ans:

- Q4. Draw the qualitative distribution of excess minority carriers (i.e. p_n' and n_p') in p⁺n junction. [2]



Q5 Write the continuity equation for electron while electric field is constant. [2]

Ans:

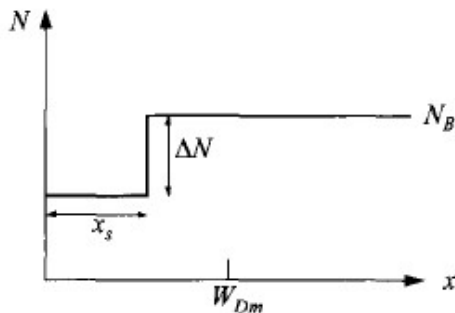
Q6. What is preferred for less shift of the threshold voltage due to effect of body bias potential (or body effect). Tick the correct answer. [1]

- (a) High/ Low substrate doping (N_A)
- (b) Thick/ Thin oxide thickness (t_{ox})

Q7. For a sharp subthreshold slope (small S), what will be the preferable combinations. Tick the correct response: [2]

- (a) High / Low channel doping,
- (b) Thick / Thin oxide thickness,
- (c) High / Low interface-trap density
- (d) High/ Low substrate bias voltage.

Q8. If the given non-uniform doping profile is used instead of a uniform doping profile for a MOSFET, what will be change in depletion width and threshold voltage. Tick the correct response. [1]



If the given non-uniform doping profile is used instead of a uniform doping profile for a MOSFET, what will be change in depletion width and threshold voltage. Tick the correct response.

- (a) Depletion width will increase / decrease
- (b) Threshold voltage will increase / decrease

Q9. Draw a schematic of a short channel MOSFET to indicate the charge sharing effect. [2]

Ans:

Q10. What is the reason behind the faster operation in SOI MOSFET as compared to the conventional bulk MOSFET? [2]

Ans:

Q11. An n-channel MOSFET having oxide thickness of 4 nm, substrate doping of $5 \times 10^{16} \text{ cm}^{-3}$, and flat band voltage of -1.1 V. Calculate the particular gate to source voltage (V_{gs}) where immediate oxide breakdown can possible at the starting of strong inversion. (Breakdown strength of SiO_2 is 18 MV/cm). [2]

Ans:

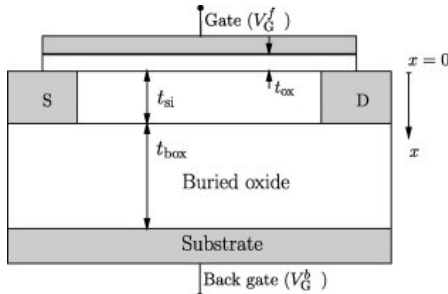
Q12. Consider an ideal MOS capacitor having n-type Si substrate. Draw the qualitative carrier (hole and electron) distribution profile under weak inversion. Ans: [2]

Q13. Draw an energy band diagram of SiO₂/Si system to indicate the band offset of ~3.1 eV. Ans: [2]

Q14. Draw a schematic of floating body in a n-channel partially depleted (PD) SOI MOSFET. Clearly indicate the all the capacitance and pn junction diodes. Ans: [2]

Q15. Sketch and label the transfer characteristics (I_D vs V_{GS}) of a n-channel **buried** device (MOSFET). Ans: [2]

Q16. Write the expressions of all three capacitances used in threshold voltage expression of the given FD-SOI-MOSFET. [3]



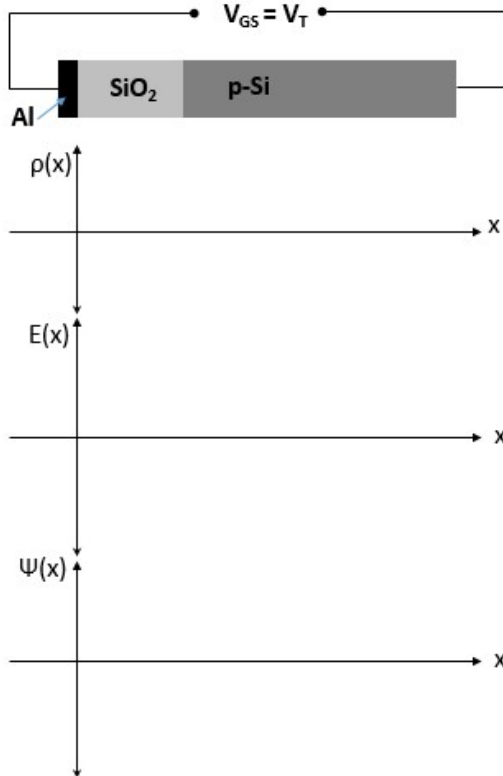
Q17. Consider 's' is the scaling factor. For, constant field scaling, write the appropriate scaled parameters. Example: Gate length (L): L/s [2]

- Doping (N_A):
- Propagation delay (τ):
- Power delay product (P.τ):
- Subthreshold slope (S):

Q18. Draw an energy band diagram of a short channel n-MOSFET to indicate the drain voltage induced barrier lowering. [2]

Q19. Draw the V_{DS} vs V_{GS} plot and indicate linear, saturation and subthreshold region. [2]

Q20. Draw the charge (ρ), electric field (E) and potential (ψ) distribution pattern for the following MOS junction at $V_{GS} = V_T$. Consider the MOS junction is ideal one. [3]



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SiO₂: $\epsilon_r=3.9$

Attempt all the questions.

Q1.

(a) Sketch and label the energy band diagram of a Metal-Silicon (M-S) junction under thermal equilibrium at 300 K. Consider, metal work function 4.1 eV, donor doping in Silicon as 5×10^{16} cm⁻³. Comment on the type of the junction. [5]

(b) Given acceptor profile $N_A(x)=N_0 e^{-ax}$. Sketch and label following quantities with respect to 'x'.

(i) Diffusion current (J_{pdiff}) [2]

(ii) Drift current (J_{pdrift}) [1]

(iii) Electric field (E_x) [2]

Q2. An abrupt p⁺n silicon junction (long base) having 10^{-4} cm² cross section with following information

p ⁺ side	n side
$N_A = 10^{17}$ cm ⁻³ , $\tau_n = 0.1$ μ s	$N_D = 10^{15}$ cm ⁻³ , $\tau_p = 10$ μ s
$\mu_p = 200$ cm ² /V-s, $\mu_n = 700$ cm ² /V-s	$\mu_n = 1300$ cm ² /V-s, $\mu_p = 450$ cm ² /V-s

At a particular bias, current is measured as 1 mA.

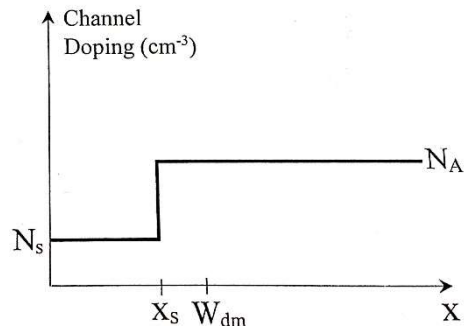
(a) Find the applied bias voltage [5]

(b) Find I_p hole current at $x = x_n$ [2]

(c) Also, find in (electron current) at $x = x_n$ [1]

(d) Sketch the hole and electron current of the p⁺n junction under forward bias. [2]

Q3. Consider an n-channel MOSFET with n⁺ polysilicon gate. Gate oxide thickness is 7 nm, fixed oxide charge 5×10^{10} cm⁻² and p-type body has a step (non-uniform) doping ($N_A \gg N_S$) as shown in the figure below. Write the threshold voltage expression considering the approximation $N_S \approx 0$ and find the value of X_s and N_A when threshold voltage is 0.3 V and corresponding surface potential ($\Psi_S=2\Psi_B$) as 1 V. Also, calculate the maximum depletion width (W_{dm}). [10]



Q4. Consider interface charges $Q_f/q=5 \times 10^{11} \text{ cm}^{-2}$ (applicable for front and back both the interfaces)

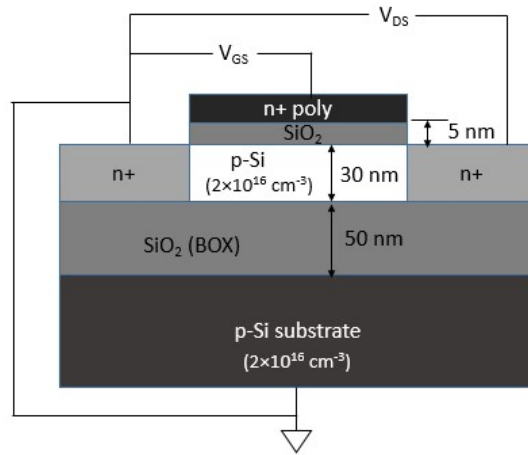
(a) Show the type of the device i.e. FD or PD SOI. [2]

(b) Find the back surface potential (Ψ_{sb}). Also, comment on the condition of the back interface (i.e. accumulation, depletion or inversion). [4]

(c) Find accurate front gate threshold voltage of the SOI MOSFET. [3]

(d) Find body factor (n) of the device and estimate V_{DSAT} for applied $V_{GS}=1 \text{ V}$. [1]

(Hint: Consider the flat band voltage in the calculation)



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